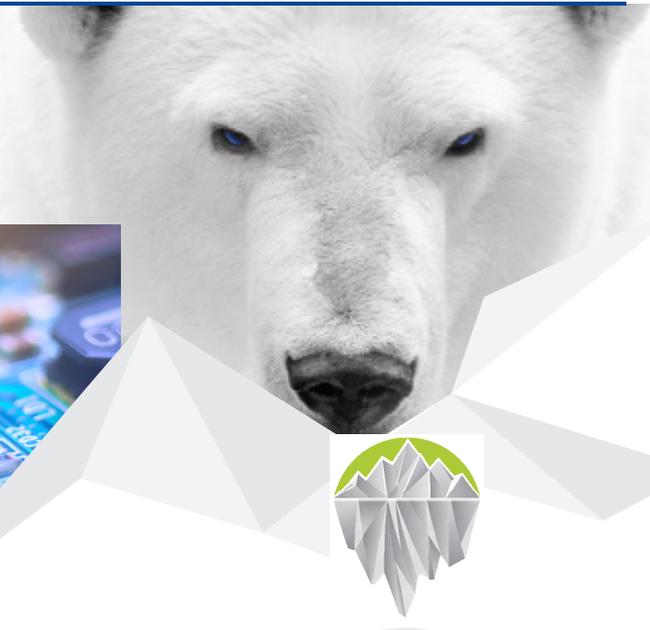
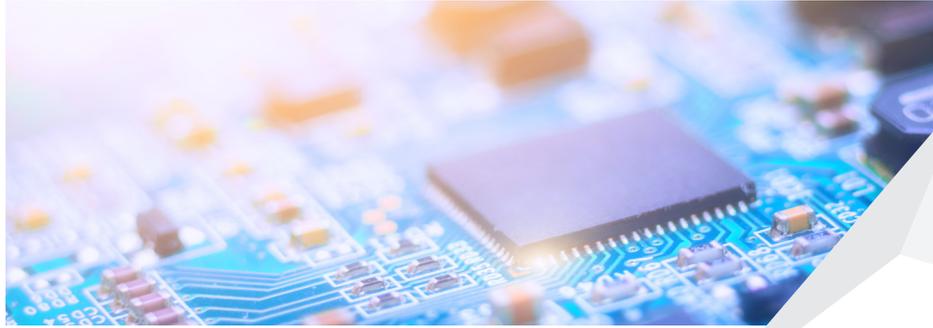




SEMICONDUCTOR

Precision cleaning of processing equipment and tooling



KEY BENEFITS

MORE EFFECTIVE CLEAN

—
CLEAN IN-PLACE
WITHOUT LENGTHY DISASSEMBLY

—
NON-ABRASIVE, NON-FLAMMABLE
& NON-CONDUCTIVE

—
REDUCTION OR ELIMINATION
OF SOLVENTS/ACIDS

—
LOWER OPERATING COSTS

—
ELIMINATION OF GRIT ENTRAPMENT

—
SAFER FOR EMPLOYEES

—
NO SECONDARY WASTE STREAM

—
ENVIRONMENTALLY FRIENDLY

In semiconductor production, the processing equipment must be kept extremely clean in order to prevent product contamination. Traditional cleaning methods present challenges, including costly downtime, the use of chemicals and solvents, hazardous waste disposal and employee exposure to harmful chemicals.

Dry ice precision cleaning is an effective method used to decontaminate semiconductor manufacturing equipment. The preparation process is aggressive enough to quickly remove deposition and contamination without impacting the substrate material.

Dry ice is non-abrasive on metal, ceramics and many other substrates and is able to quickly remove all surface contaminants from even the most difficult areas of the processing equipment without creating a secondary waste stream.

Industry Leaders Benefiting from Cold Jet

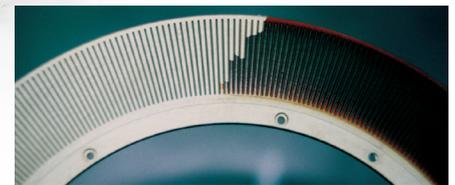


FEATURED APPLICATIONS

- WAFERS
- MASKS/SHIELDS
- CHEMICAL MECHANICAL POLISHING (CMP)
- VACUUM PUMPS

- CONFORMAL COATING REMOVAL OFF PCB
- POLISHING TOOLING
- WAFER CHAMBER TOOLING AND COMPONENTS

- IMPLANTERS
- CERAMIC SUPPORT DISCS
- POLYCRYSTALLINE SILICONE REACTORS
- DEPOSITION TOOLING



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